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Orderable: N/A	Designed for: Public Release	Mod. Date: 11/3/2015	 http://www.ti.com <small>© Texas Instruments 2015</small>
Number:	Rev: A	TID#: TIDM-CAPTIVATE-THERMOSTAT-UI	
SVN Rev: Version control disabled	Assembly Variant: TI Design	Sheet: 2 of 2	
Drawn By:	File: TIDM_CAPTIVATE_THERMOSTAT_UI.Sch	Size: B	
Engineer: W. Schnoor	Contact: http://www.ti.com/support		

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